



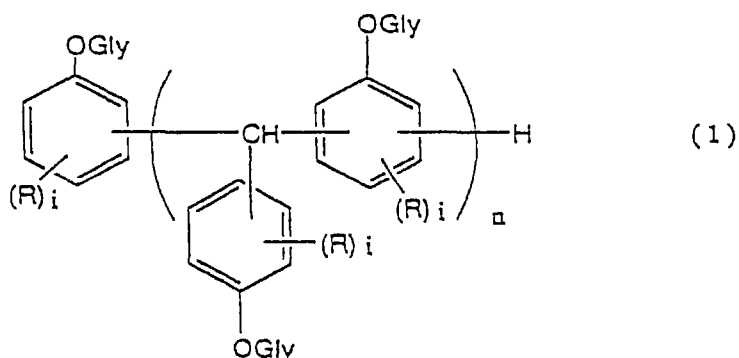
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ABSTRACT OF THE DISCLOSURE

THERMOSETTING RESIN COMPOSITION FOR BUILD-UP METHOD

Provided are a thermosetting resin composition for build-up method which gives a cured product excellent in heat resistance, an insulating material for build-up method using thereof and a build-up print circuit board.

The thermosetting resin composition for build-up method comprises (A) an epoxy resin represented by formula (I), (B) a curing agent for epoxy resin and (C) a poly(ether sulfone), an insulating material for build-up method and a build-up print circuit board using thereof.



in the formula, Gly represents glycidyl group; R represents each independently, an alkyl group having 1 to 10 carbons, and the like; i represents each independently a numeral of 0 to 4; when i is 2 or more, R may be the same or different from each other; and n represents a repeating number of 1 to 10.



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